

# Global System in Package Supply, Demand and Key Producers, 2026-2032

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## Abstracts

The global System in Package market size is expected to reach \$ 10558 million by 2032, rising at a market growth of 5.2% CAGR during the forecast period (2026-2032).

System in Package (SiP) refers to a package/module that realizes a functional electronic system (or subsystem) by integrating and miniaturizing multiple active dies (logic/PMIC/RF/memory, etc.) and often passives within a single package footprint, using IC assembly/packaging technologies rather than monolithic integration on one die. In practice, SiP is a mainstream form of heterogeneous integration?i.e., combining separately manufactured components into a higher-level assembly (SiP) to achieve better functionality/operating characteristics under tight size/power constraints. SiP is delivered as a turnkey ?design + manufacturing + test? service with higher engineering content than conventional single-die packages. Leading OSATs explicitly position SiP as including system co-design (EDA/RF/antenna/shielding/substrate layout), simulation (electrical/thermal/mechanical), module testing and manufacturing execution?often bundled with upstream wafer probe and downstream final test/SLT depending on customer procurement strategy. The supply chain is correspondingly broader: upstream includes dies, passives, organic substrates (incl. thin/coreless variants), embedded-substrate options, interconnect materials (bumps/solder/underfill), molding/shielding materials, plus equipment for placement, interconnect, molding, RDL/fan-out (where applicable) and test; midstream comprises OSATs and module integrators executing SiP NPI-to-HVM; downstream spans OEMs/ODMs and end markets where module-level integration shortens design cycles and reduces PCB area.

Current development is shaped by (i) device/function disaggregation and chipletization that pushes more functionality into package-level integration, (ii) higher interconnect density and shorter connections demanded by heterogeneous integration, and (iii) the

pull from compact systems (wearables/5G/IoT) and advanced packaging, including foundry-side fan-out PoP being used inside SiP modules (e.g., Apple Watch Series 9 SiP using TSMC InFO-PoP observed in teardown analysis). As a result, the competitive ?must-haves? are system co-design, robust thermal/EMI management, high-yield multi-die assembly, and high-coverage module test?rather than pure packaging capacity.

The SiP competitive set is multi-layered: tier-1 OSATs anchor the market because they can industrialize high-mix multi-die assembly with system co-design and module test?ASE explicitly positions SiP as a turnkey capability including design (EDA/RF/antenna/shielding/substrate layout), simulation and module testing, while Amkor markets SiP for mobile/RF/wearables/automotive and positions itself as a leader in SiP design/assembly/test. Module integrators and passive-substrate innovators also matter (e.g., TDK has promoted SiP module strategies and embedded-substrate routes and has publicly partnered with ASE around embedded solutions), and specialized R&D/packaging institutes (e.g., A\*STAR IME) develop SiP architectures for data centers, mobile/5G, IoT, AI and automotive. Meanwhile, foundries are selectively participating where wafer-level fan-out and PoP integration are strategic?public teardown commentary has highlighted Apple Watch SiP implementations using TSMC InFO-PoP, illustrating that ?SiP? spans both OSAT module builds and foundry-enabled wafer-level platforms depending on product architecture. Competition increasingly centers on system co-design depth, thermal/EMI integrity, yield learning across heterogeneous components, and module-level test coverage, rather than the commodity notion of packaging capacity.

This report studies the global System in Package production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for System in Package and provides market size (US\$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of System in Package that contribute to its increasing demand across many markets.

### **Highlights and key features of the study**

Global System in Package total production and demand, 2021-2032, (Million Units)

Global System in Package total production value, 2021-2032, (USD Million)

Global System in Package production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Million Units), (based on production site)

Global System in Package consumption by region & country, CAGR, 2021-2032 & (Million Units)

U.S. VS China: System in Package domestic production, consumption, key domestic manufacturers and share

Global System in Package production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Million Units)

Global System in Package production by Packaging Platform, production, value, CAGR, 2021-2032, (USD Million) & (Million Units)

Global System in Package production by Functional Type, production, value, CAGR, 2021-2032, (USD Million) & (Million Units)

This report profiles key players in the global System in Package market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Amkor Technology, Inc., Intel Corporation, ASE Technology Holding Co., Ltd. / ASE, Powertech Technology Inc. (PTI), King Yuan Electronics Co., Ltd. (KYEC), ChipMOS Technologies Inc., Ardentec Corporation, Sigurd Microelectronics Corporation, Greatek Electronics Inc., Chipbond Technology Corporation, etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World System in Package market

### **Detailed Segmentation:**

Each section contains quantitative market data including market by value (US\$ Millions), volume (production, consumption) & (Million Units) and average price (US\$/Unit) by manufacturer, by Packaging Platform, and by Functional Type. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global System in Package Market, By Region:

United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

#### Global System in Package Market, Segmentation by Packaging Platform:

Laminate-based SiP

Package-on-Package / stacked SiP

Fan-out / RDL-based SiP

Embedded component/substrate SiP

2.5D/3D (interposer/TSV) system package

#### Global System in Package Market, Segmentation by Interconnect:

Wire-bond dominant

Flip-chip dominant

Mixed interconnect

TSV / hybrid bonding class

#### Global System in Package Market, Segmentation by Functional Type:

RF front-end / antenna modules

Connectivity modules

Wearables SiP

Power management / PMIC modules

Sensor/optical/IMU modules

Automotive SiP modules

Others

#### Companies Profiled:

Amkor Technology, Inc.

Intel Corporation

ASE Technology Holding Co., Ltd. / ASE

Powertech Technology Inc. (PTI)

King Yuan Electronics Co., Ltd. (KYEC)

ChipMOS Technologies Inc.

Ardentec Corporation

Sigurd Microelectronics Corporation

Greatek Electronics Inc.

Chipbond Technology Corporation

Walton Advanced Engineering, Inc. (WAE)

Orient Semiconductor Electronics, Ltd. (OSE)

Universal Scientific Industrial Co., Ltd. (USI)

Taiwan Semiconductor Manufacturing Company (TSMC)

JCET Group Co., Ltd.

Tongfu Microelectronics Co., Ltd.

Tianshui Huatian Technology Co., Ltd.

SJ Semiconductor Corporation (SJ Semi)

Forehope Electronic (Ningbo) Co., Ltd.

UTAC Group

STATS ChipPAC

Unisem Group

Carsem (M) Sdn. Bhd.

Inari Amertron Berhad

### **Key Questions Answered:**

1. How big is the global System in Package market?
2. What is the demand of the global System in Package market?
3. What is the year over year growth of the global System in Package market?
4. What is the production and production value of the global System in Package market?
5. Who are the key producers in the global System in Package market?
6. What are the growth factors driving the market demand?

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